

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently Amended) A semiconductor device comprising:

a lead frame having a die pad, supporting leads continuously formed with said die pad, and a plurality of leads, first ends of said plurality of leads being disposed to surround said die pad in a plane view;

a semiconductor chip mounted on said die pad, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of said semiconductor chip, said die pad having a size which is smaller than that of said semiconductor chip;

a plurality of bonding wires electrically connecting said bonding pads with the first ends of said plurality of leads respectively; and

a resin body sealing said semiconductor chip, said die, said supporting leads, portions of the plurality of leads and said plurality of bonding wires,

wherein a pitch between first ones of adjacent bonding pads at each of four corners defined by said four sides of said main surface of said semiconductor chip is wider than a pitch between second ones of adjacent bonding pads which are disposed at a relatively central position of each of said four sides as compared to said four corners, and wherein a pitch between tips of first ones of adjacent leads at each of said four corners is wider than a pitch between tips of second ones of adjacent leads which are disposed at said relatively central position of each of said four sides as compared to said four corners.

2. (Original) A semiconductor device according to claim 1, wherein said semiconductor chip is bonded to said die pad by an adhesive.
3. (Original) A semiconductor device according to claim 2, wherein said die pad has a circular shape in said plane view.
4. (Original) A semiconductor device according to claim 2, wherein said die pad has a cross shape in said plane view.
- 5.. (Original) A semiconductor device according to claim 2, wherein said resin member is formed in a tetragonal shape, and wherein portions of said plurality of leads protrude outwardly from said resin member at four sides of said resin member.
6. (Original) A semiconductor device according to claim 2, wherein a part of said resin member contacts with a rear surface of said semiconductor chip except for areas to which said die pad is bonded.
7. (New) A semiconductor device according to claim 1, wherein a pitch between adjacent bonding pads increases stepwise from said relatively central position of each of said four sides to said four corners.